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ABSTRACT OF THE DISCLOSURE

A method of manufacturing a semiconductor device substrate includes the steps of: arranging on a base a temporary fixing member for temporarily fixing an
5 electronic component; temporarily fixing the electronic component on the base by the temporary fixing member; forming a substrate body on the base and the electronic component; removing a portion of the base which portion corresponds to the electronic component, thereby exposing
10 the temporary fixing member; and removing the temporary fixing member, thereby enabling the electronic component to make an external connection.